

# PFR<sup>®</sup>-800 AUS<sup>®</sup> SR1 (Trial #63207)

**NEW**

## FC用現像型ソルダーレジストドライフィルム

### Dry Film Solder Resist for Flip Chip Substrate Application

#### 特長 Features

- 超高感度・投影露光/LDI (マルチ/シングル・ライン) 露光対応  
Super photosensitive for high speed exposure (Projection, LDI multi/single line)
- 高Tg/低CTE材:優れたTCT/PCT耐性 Tough resin structure with High Tg/Low CTE for TCT and PCT resistance
- 高精細での優れた電気特性 Electrical reliability : No migration failure with L/S 15/10 $\mu$ m after 200hrs,130 $^{\circ}$ C/85%Rh,12V
- 徹底した粗粒管理 Strict control on particle size : Max.particle size <10 $\mu$ m. Majority part is sub-micron order

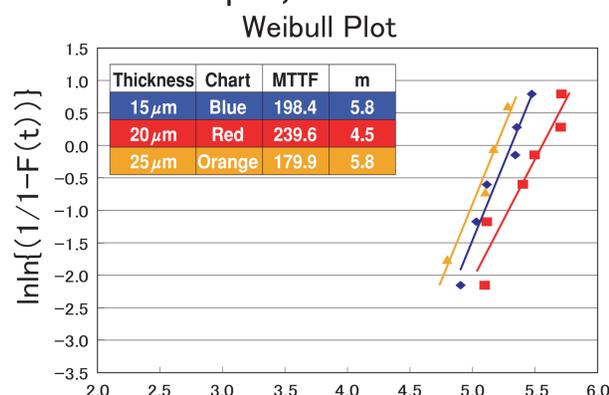
#### 仕様 Specifications

膜厚 Resin thickness	20 $\mu$ m (standard)- Adjustable
色調 Color	Green
保管条件 Storage condition	Below -15 $^{\circ}$ C
推奨硬化条件 Recommended curing condition	160 $^{\circ}$ C, 60min.

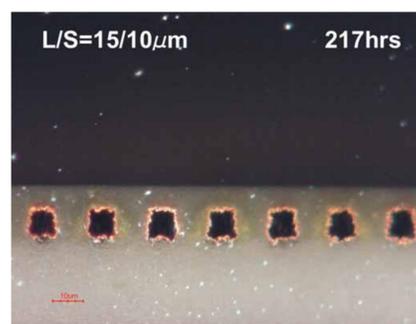
#### 特性 Properties

ガラス転移点 Tg *TMA method	135 $^{\circ}$ C	
線膨張係数 CTE	$\alpha$ 1	55ppm
弾性率 Young's modulus	3200 MPa	
破壊強度 Tensile strength	75 MPa	
破壊伸び率 Elongation	4.5 %	
感度 Photosensitivity	100 mJ/cm <sup>2</sup>	
解像性 SRO resolution	50 $\mu$ m in diameter	
PCT耐性 (121 $^{\circ}$ C, 2.1atm, 100%Rh, 200hrs)	No peering	
HAST 耐性 (130 $^{\circ}$ C, 85%Rh, 12V, 200hrs, L/S=15/10 $\mu$ m)	No migration	
TCT 耐性 (-65 $\leftrightarrow$ 150 $^{\circ}$ C, 1000cycles)	Pass	

Weibull plot in BHAST  
L/S15/10 $\mu$ m, 130 $^{\circ}$ C/85% 12V



After 217hrs HAST  
130 $^{\circ}$ C/85%12V



SRO 50 $\mu$ m by USHIO Projector  
100mJ/cm<sup>2</sup>

